

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A packaged semiconductor device comprising:

a first semiconductor die disposed over a package substrate, said first semiconductor die coupled to said package substrate;

a plurality of wire bonds coupled to said first semiconductor die and coupled to said package substrate for electrically coupling said first semiconductor die to said package substrate;

a first layer of encapsulant disposed over said first semiconductor die and disposed over said plurality of wire bonds so as to completely cover said plurality of wire bonds; and

a second semiconductor die disposed over said first layer of encapsulant and coupled to said first layer of encapsulant, said second semiconductor die electrically coupled to said package substrate.

2. (original) The packaged semiconductor device of Claim 1 wherein said second semiconductor die is directly coupled to said first layer of encapsulant using adhesive.

3. (original) The packaged semiconductor device of Claim 2 wherein said second semiconductor die at least partially overlies said first semiconductor die.

4. (previously presented) The packaged semiconductor device of Claim 2 wherein only portions of said first layer of encapsulant, portions of said plurality of wire bonds and said adhesive extend between said first semiconductor die and said second semiconductor die.

5. (original) The packaged semiconductor device of Claim 2 wherein no spacer is disposed between said first semiconductor die and said second semiconductor die.

6. (original) The packaged semiconductor device of Claim 2 wherein said package substrate is a ball grid array package substrate.

7. (previously presented) The packaged semiconductor device of Claim 6 further comprising:

an additional set of wire bonds, said additional set of wire bonds coupled to said second semiconductor die and coupled to said ball grid array package substrate for electrically coupling said second semiconductor die to said ball grid array package substrate; and

a second layer of encapsulant disposed over said second semiconductor die and disposed over said additional set of wire bonds.

8. (currently amended) The packaged semiconductor device of Claim 4 2 wherein said adhesive comprises a silver-filled epoxy adhesive.

9 21. (currently amended) A packaged semiconductor device comprising:

a first semiconductor die disposed over a package substrate, said first semiconductor die coupled to said package substrate;

a plurality of wire bonds coupled to said first semiconductor die and coupled to said package substrate for electrically coupling said first semiconductor die to said package substrate;

a first layer of encapsulant disposed over said first semiconductor die and disposed over said plurality of wire bonds so as to completely cover said plurality of wire bonds; and

a second semiconductor die disposed over said first layer of encapsulant, said second semiconductor die attached to said first layer of encapsulant using adhesive, said second semiconductor die electrically coupled to said package substrate.

~~10~~ 22. (currently amended) The packaged semiconductor device of Claim 9 21 wherein said second semiconductor die at least partially overlies said first semiconductor die.

~~44~~ 23. (currently amended) The packaged semiconductor device of Claim ~~9~~ 21 wherein only portions of said first layer of encapsulant, portions of said plurality of wire bonds and said adhesive extend between said first semiconductor die and said second semiconductor die.

~~42~~ 24. (currently amended) The packaged semiconductor device of Claim ~~9~~ 21 wherein no spacer is disposed between said first semiconductor die and said second semiconductor die.

~~43~~ 25. (currently amended) The packaged semiconductor device of Claim ~~42~~ 24 wherein said package substrate is a ball grid array package substrate.

~~44~~ 26. (currently amended) The packaged semiconductor device of Claim ~~9~~ 21 further comprising:

an additional set of wire bonds, said additional set of wire bonds coupled to said second semiconductor die and coupled to said package substrate for electrically coupling said second semiconductor die to said package substrate.

~~45~~ 27. (currently amended) The packaged semiconductor device of Claim ~~44~~ 26 further comprising:

a second layer of encapsulant disposed over said second semiconductor die and disposed over said additional set of wire bonds.

46 28. (currently amended) The packaged semiconductor device of Claim 9 21
wherein said adhesive comprises a silver-filled epoxy adhesive.

47 29. (currently amended) A packaged semiconductor device comprising:

a first semiconductor die disposed over a package substrate, said first
semiconductor die coupled to said package substrate;

a first set of wire bonds coupled to said first semiconductor die and coupled to
said package substrate for electrically coupling said first semiconductor die to said
package substrate;

a first layer of encapsulant disposed over said first semiconductor die and
disposed over said first set of wire bonds so as to completely cover said first set of wire
bonds;

a second semiconductor die disposed over said first layer of encapsulant, said
second semiconductor die attached to said first layer of encapsulant using adhesive;
and

a second set of wire bonds, said second set of wire bonds coupled to said
second semiconductor die and coupled to said package substrate for electrically
coupling said second semiconductor die to said package substrate.

~~18~~ 30. (currently amended) The packaged semiconductor device of Claim ~~17~~ 29
further comprising:

a second layer of encapsulant, said second layer of encapsulant disposed over
said second semiconductor die and disposed over said second set of wire bonds.

~~19~~ 31. (currently amended) The packaged semiconductor device of Claim ~~17~~ 29
wherein only portions of said first layer of encapsulant, portions of said first set of wire
bonds and said adhesive extend between said first semiconductor die and said second
semiconductor die.

~~20~~ 32. (currently amended) The packaged semiconductor device of Claim ~~17~~ 29
wherein no spacer is disposed between said first semiconductor die and said second
semiconductor die.

Amendments to the Drawings

The attached two sheets of drawings include changes to Figures 4 and 10. These sheets, which include Figures 2, 4, 8 and 10, replace the original two sheets that include Figures 2, 4, 8 and 10. In Figures 4 and 10 the numeral 19 has been changed to 29.

Attachment: Replacement Sheets (2)

Annotated Sheets (2) Showing Changes